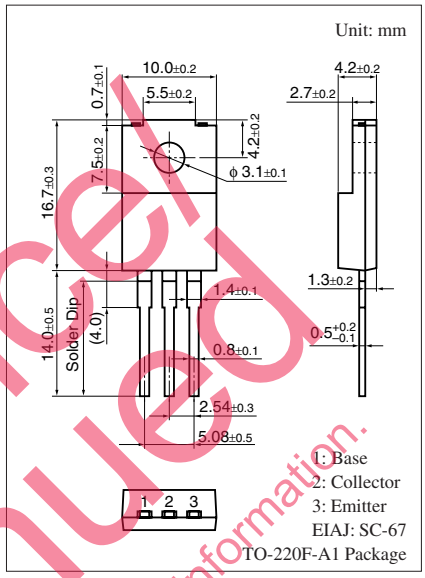
2SB1063

Silicon PNP triple diffusion planar type

For high power amplification
Complementary to 2SD1499



■ Features

- Extremely satisfactory linearity of the forward current transfer ratio h_{FE}
- Wide safe operation area
- High transition frequency f_T
- Full-pack package which can be installed to the heat sink with one screw

■ Absolute Maximum Ratings $T_C = 25°C$

Parameter	Symbol	Rating	Unit
Collector-base voltage (Emitter open)	V_{CBO}	−100	V
Collector-emitter voltage (Base open)	V_{CEO}	−100	V
Emitter-base voltage (Collector open)	V_{EBO}	−5	V
Collector current	I_C	−5	A
Peak collector current	I_{CP}	−8	A
Collector power dissipation	P_C	40	W
$T_a = 25°C$		2.0	
Junction temperature	T_j	150	°C
Storage temperature	T_{stg}	−55 to +150	°C

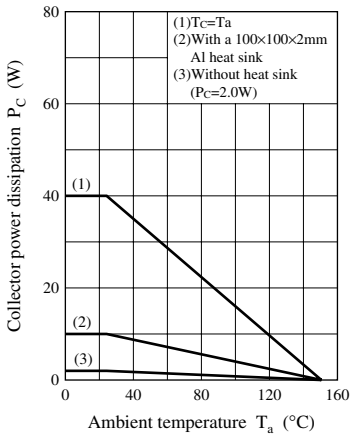
■ Electrical Characteristics $T_C = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Base-emitter voltage	V_{BE}	$V_{CE} = -5$ V, $I_C = -3$ A			−1.8	V
Collector-base cutoff current (Emitter open)	I_{CBO}	$V_{CB} = -100$ V, $I_E = 0$			−50	μA
Emitter-base cutoff current (Collector open)	I_{EBO}	$V_{EB} = -3$ V, $I_C = 0$			−50	μA
Forward current transfer ratio	h_{FE1}	$V_{CE} = -5$ V, $I_C = -20$ mA	20			—
	h_{FE2} *	$V_{CE} = -5$ V, $I_C = -1$ A	40		200	
	h_{FE3}	$V_{CE} = -5$ V, $I_C = -3$ A	20			
Collector-emitter saturation voltage	$V_{CE(sat)}$	$I_C = -3$ A, $I_B = -0.3$ A			−2	V
Transition frequency	f_T	$V_{CE} = -5$ V, $I_C = -0.5$ A, f = 1 MHz		20		MHz
Collector output capacitance (Common base, input open circuited)	C_{ob}	$V_{CB} = -10$ V, $I_E = 0$, f = 1 MHz		170		pF

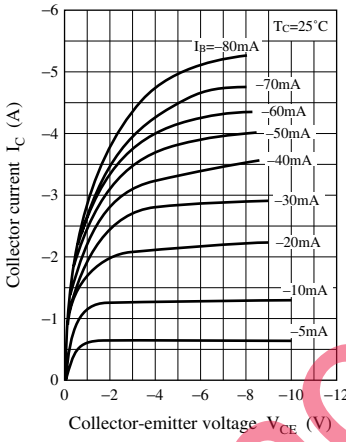
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.
2. *: Rank classification

Rank	R	Q	P
h_{FE2}	40 to 80	60 to 120	100 to 200

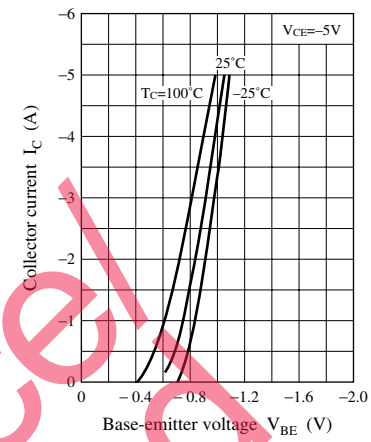
P_C — T_a



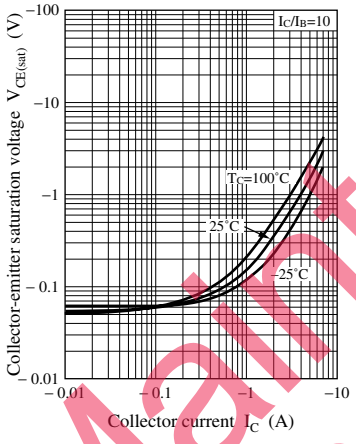
I_C — V_{CE}



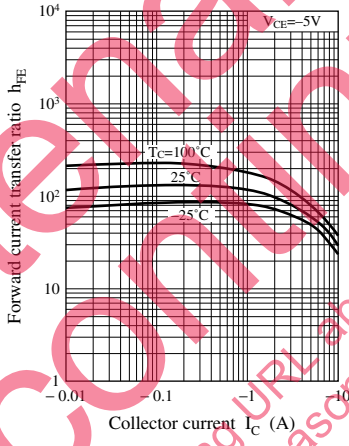
I_C — V_{BE}



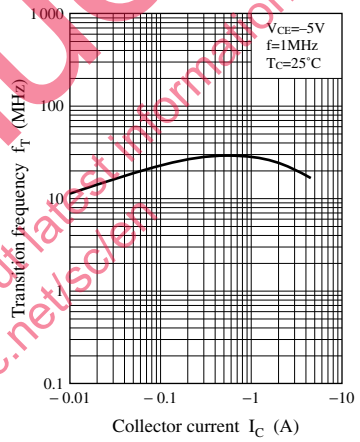
$V_{CE(sat)}$ — I_C



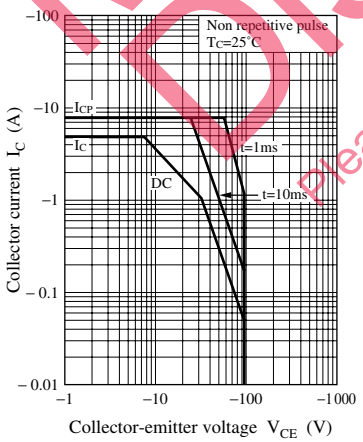
h_{FE} — I_C



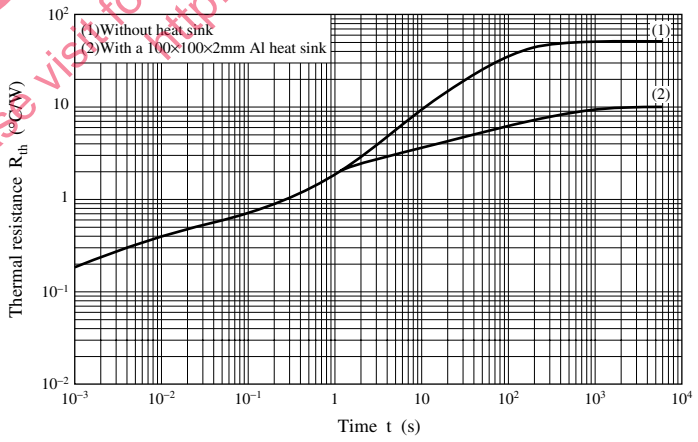
f_T — I_C



Safe operation area



R_{th} — t



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